

Special Issue

Heat Transfer across Nanoparticles

Message from the Guest Editor

Dear colleagues, The Special Issue will deal with nanoscale heat transfer across individual nanoparticles, between contacting nanoparticles, and across the interface between a nanoparticle and the surrounding fluid (gas or liquid). We solicit contributions dealing with the controlling mechanisms determining heat transfer rates at these nanoscale interfaces. Studies involving analytical, numerical, or experimental investigations of thermal transport across, through, and between nanoparticles, as well as novel heat transfer applications involving nanoparticles are welcome.

- Nanoparticles
- Heat Transfer
- Molecular Dynamics Simulations
- Nanoscale Interface
- Nanofluid
- Aerogel

Guest Editor

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Deadline for manuscript submissions

closed (15 November 2018)



Applied Sciences

an Open Access Journal
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Impact Factor 2.5
CiteScore 5.5



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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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